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PRODUCT AND PROCESS CHANGE NOTIFICATION
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This notice is Freescale Confidential Proprietary and is only intended for the customer listed on this notification.

ISSUE DATE:	16-Jan-2015
NOTIFICATION:	16592
TITLE:	LQFP48/32 7x7x1.4mm Assembly Site Expand to Nantong Fujitsu Microelectronics Co., Ltd
EFFECTIVE DATE:	16-Apr-2015

DEVICE(S)

MPN
MC9S08FL16CLC
MC9S08FL8CLC
MC9S08JM16CLC
MC9S08JM8CLC
MC9S08LL16CLF
MC9S08LL8CLF
MC9S08MP16VLC
MC9S08MP16VLCR
MC9S08PA16AVLC
MC9S08PA16AVLCR
MC9S08PA16VLC
MC9S08PA16VLCR
MC9S08PA32AVLC
MC9S08PA32AVLF
MC9S08PA32VLC
MC9S08PA32VLF
MC9S08PA60AVLC
MC9S08PA60AVLF
MC9S08PA60VLC
MC9S08PA60VLF
MC9S08PA60VLFR
MC9S08PA8AVLC
MC9S08PA8VLC
MC9S08PT16AVLC
MC9S08PT16VLC
MC9S08PT16VLCR
MC9S08PT32AVLC
MC9S08PT32AVLF
MC9S08PT32VLC
MC9S08PT32VLCR
MC9S08PT32VLF

MC9S08PT60AVLC
MC9S08PT60AVLF
MC9S08PT60VLC
MC9S08PT60VLF
MC9S08PT8AVLC
MC9S08PT8VLC
MC9S08QE16CLC
MC9S08QE32CLC
MC9S08QE32CLCR
MKE02Z16VLC2
MKE02Z16VLC4
MKE02Z32VLC2
MKE02Z32VLC2R
MKE02Z32VLC4
MKE02Z64VLC2
MKE02Z64VLC4

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AFFECTED CHANGE CATEGORIES

- ASSEMBLY SITE

DESCRIPTION OF CHANGE

Freescale Semiconductor is announcing the assembly site expansion for the products listed in this notification from the current Freescale Tianjin Final Manufacturing (TJNFM), Tianjin, China assembly Facility to the Nantong Fujitsu Microelectronics Co., Ltd. (NFME), Nantong, China assembly Facility

Table below provides the sample part number:

Sample Part Number	Package Description
PC9S08PT60VLF	LQFP 48 7*7*1.4P0.5
PC9S08JM16CLC	LQFP 32 7*7*1.4P0.8

REASON FOR CHANGE

Qualification of the Nantong Fujitsu Microelectronics Co., Ltd. (NFME), Nantong, China assembly Facility to improve manufacturing flexibility and customer support.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

There is no impact on device form, fit, function or reliability.

According to JEDEC Standard JESD46, lack of acknowledgement of this PCN within 30 days will be considered acceptance of change. To request further data or inquire about the notification, please enter a Service Request.

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 20-Mar-2015

QUALIFICATION STATUS: IN PROCESS

QUALIFICATION PLAN:

Freescale Semiconductor Manufacturing standard specification for assembly transfers was followed for the Assembly Transfer.

RELIABILITY DATA SUMMARY:

Will provide upon request.

ELECTRICAL CHARACTERISTIC SUMMARY:

No change was made to the operating performance of the device. Electrical characterization of the device was not required.

CHANGED PART IDENTIFICATION:

The assembly site, among other information, is reflected in the package trace code.

The current assembly site marking for site1 TJNFM is A=CT.
The marking for proposed assembly site2 NFME is A = XN.

SAMPLE AVAILABILITY DATE: 12-Jan-2015

ATTACHMENT(S):
External attachment(s) FOR this notification can be viewed AT:
16592_Eject_pin_mark_difference_between_TJN_and_NFME_.pdf